CUSTOI	MER'S	NAME
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ALPHA REFERENCE NO.

SP15110146

SPECIFICATION

PART NO.	ALPHA MODEL NAME							
	RA6020F-20-15C2-A100K							
	·							

MODEL NAME		
MODEL NO.		

-		APPI	ROVAL	
	•			

PREPARED BY	REVIEWED BY	APPROVED BY
登 2015 .11. 225 彩霞		李 2015 11: 25. 延玲



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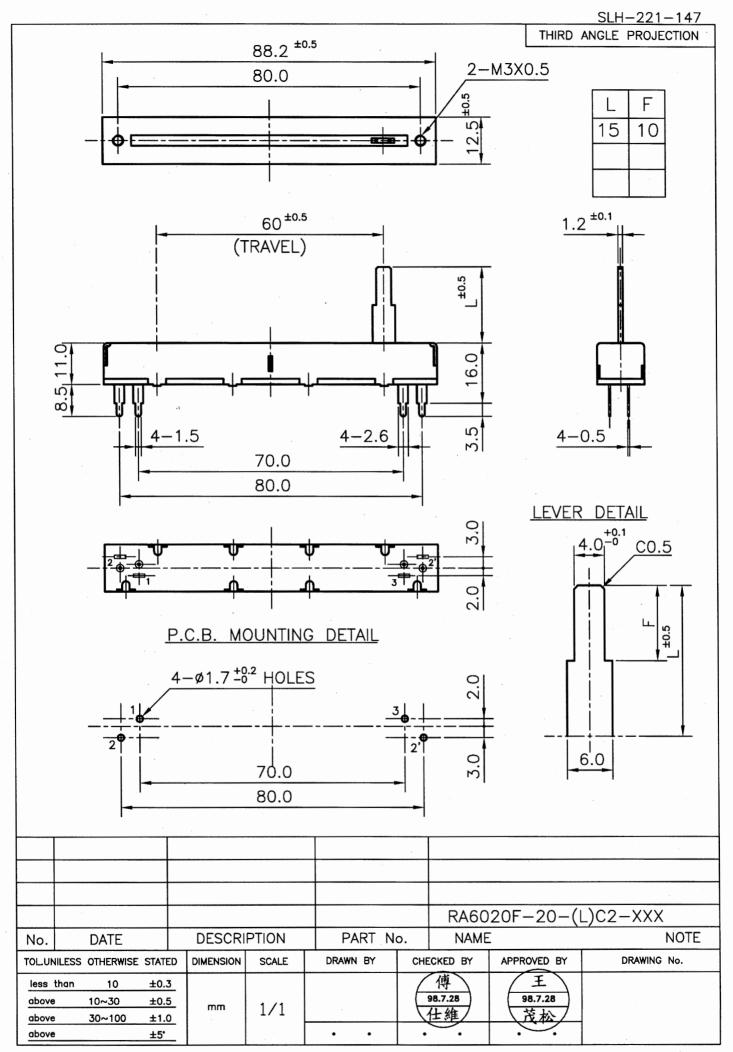
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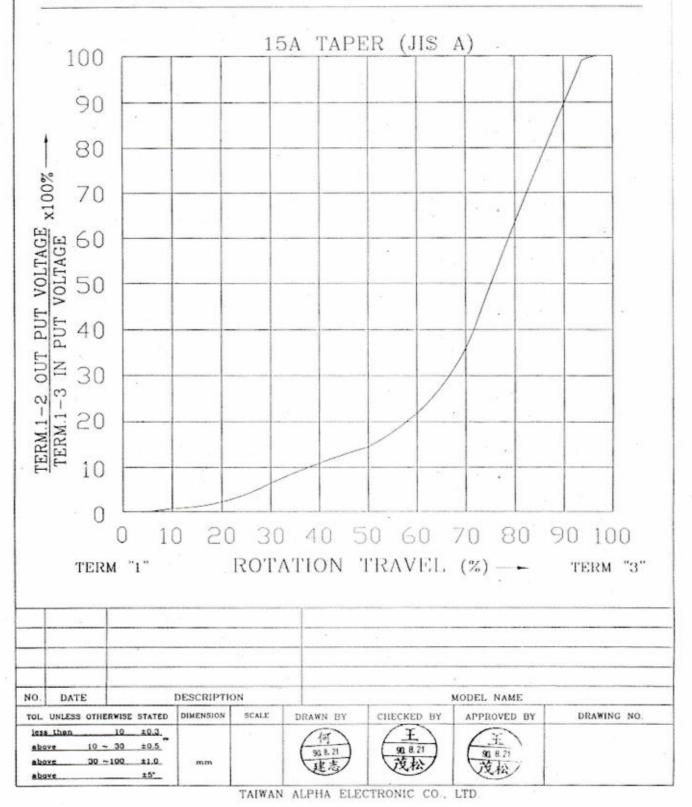
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CUSTOMER'S NAME			NOTE							DATE			
CUSTOMER'S PART NAME													
CUSTOMER'S DRAWING NO.													
1. MECHANICAL SPECIFICATION						2. ELECTR	ICAL SPE	CIFICATION	<u> </u>	·			
1. OUTSIDE DIMENSION	append	l fig.				1. OVERALL RE	SISTANCE &	TOLERANCE	terminal 1-	.3 10	00K.	Ω± 20	%
2. TOTAL ROTATION ANGLE	degr	ee			±5°	2. TAP RESIST.	ANCE & TOI	LERANCE	terminal 1-	-4		Ω±	%
3. TOTAL TRAVEL STROKE	mr	n	6	0	±0.5	3. RATED WAT	TAGE		temp 0~50°	°C		0.25	W
4. NUT WIRING STRENGTH	twisting r	noment	less than	l	kgf.cm	4. MAXIMUM	WORKING V	OLTAGE O	AC			35 0	V
5. SCREW TIGHTENING FORCE	torsional	noment	less than	. 2	kgf.cm	5. RESISTANCE	TAPER MEAS	SURING POINT			5() %j	oint
6. ROTATION TORQUE	speed 60	deg/sec.			gf.cm	& TOLERANCE	Е				40	~ 60) %
7. SLIDING FORCE	speed 201	nm/sec	50~3	50	gf.cm	6. RESIDUAL I	RESISTANCE	3	terminal 1/3 s	side les	s than	20/30	Ω
8. SHAFT LEVER STRENGTH	pulling p	ushing	more tha	n	kgf.cm	7. TAP RESIDU	AL RESISTA	NCE	terminal 4 si	ide les	s than	100	Ω.
9. SHAFT LEVER WOBBLE	2(2XL)/20mm N	lax.(L:LEVE	R LENGTH	ВОТ	H SIDES)	8. SLIDE NOIS	E			les	s than	47	mV
10. SHAFT LEVER STOP STRENGTH	more than 5	kgf.cm (st	atic load) /	6	0 sec	9. INSULATION	N RESISTAN	CE	more than	00 M	Ω(D <u>C</u>	500	V)
more than 500 gf.cm / 10			10. WITHSTAND VOLIMOL		AC 50	00 V		1 m	inute				
11. TERMINAL STRENGTH soldering heat 350±5°C/3sec. 2 resist change within ± 2%		200gf.cm/10 ±1sec 111. TRACKING ERROR											
12 CLICK DOCUTION & TOPOLIE	gf.c.			•		12. SWITCH CO	NTACT RES	ISTANCE	МΩ	less	than		m Ω
12. CLICK POSITION & TORQUE	1					13. SWITCH RA	ΓING		•				
13. SWITCH WORKING ANGLE (STROKE									-				
14. SWITCH WORKING TORQUE (FORCE	gi.c	<u> </u>				3. USABLE	TEMPER	ATURE RAN	GE: from –10	°C to 70°	C		
15. SWITCH CIRCUIT	1					4. VR LIFE	15,000	±	TIMES	•			
SHAFT							RESISTA	ANCE CHAN	NGE: within ±	<u>.</u>		%	
		DD (E)	IGION				SLIDE N	NOISE : less t	than			mV	
MATERIAL θ		DIMEN				SW LIFE		<u>+</u>	TIMES				
	at M	L	F	Т	`		CONTAC	CT RESISTA	NCE: less tha	an		m	Ω
		15					0 01 1212		4				-
						REFI	ERENCE NO.				RE'	V	
MODEL NAME DRA		AWING 1	NO.										
RA6020F-20-15C2-A1	00K												
										<u> </u>			

STANDARD RESISTANCE TAPER



可變電阻無鉛焊錫與保管條件共通規格書

Common Specification of Lead-Free Soldering and Storage conditions for Potentiometers

以下焊錫條件以可變電阻置於單層 1.6mm 厚度之印刷電路板上測試爲基準.

The specification below is based on testing results of 1.6mm thickness single layer printed circuit board.

1. 手工焊錫條件:

For Manual Soldering:

- 1-1 操作溫度最高 350°C,操作時間 3 秒以內。
 - To be performed within 3 seconds at 350°C or below.
- 2. 自動或半自動機台焊錫條件:

For Automated or Semi-Automated Soldering Equipments:

- **2-1** 使用發泡式且比重 **0.82** 以上的助焊劑,發泡高度以印刷電路板厚度一半為標準,且助劑不能流入可變電阻基板表面及印刷電路板表面。
 - Flux of 0.82 specific gravity, applied by foam fluxer, shall be used. Foam head shall be limited to the height which is half thickness of printed circuit board to be soldered. No flux should be allowed to run up onto resistive element board of potentiometer and the surface of printed circuit board.
- 2-2 預熱時間不超過兩分鐘,焊錫接面 (即印刷電路板底) 最高預熱溫度不超過 100°C。 Regarding preheating, the entire flow duration should not exceed 2 minutes, and soldering surface temperature (undersurface of PCB) shall be settled within 100°C.
- 2-3 焊錫過程機台設定溫度在 260°C 以下、 4 秒以內。
 Solder Dipping is to be performed within 4 seconds at 260°C or below.
- 3. 若回轉型電位器是塑膠軸且帶有檔位,請將主軸先調整至其中一個檔位或中心檔位上才可以 進行焊錫作業。

For rotary potentiometer with plastic shaft which have centre detent or multiple detents, the shaft should be settled in relevant detent position prior to soldering process.

4. 手工焊錫、自動或半自動機台焊錫不得超過一回。

Regardless of soldering facility and method, solder dipping or solder smearing must not be carried out more than 1 time.

註: 本項焊錫溫度條件不適用於回流焊接作業設備。

Remarks: This specification is not recommended for and applicable in reflow soldering.

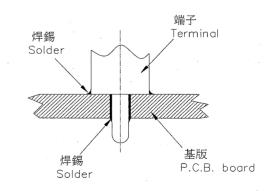
焊錫注意事項:

Caution for soldering:

如圖所示,請避免 PCB 上層表面有焊錫 Please avoid soldering on upper surface of P.C.B. as shown.

5. 保管條件(Storage conditions):

產品需儲存在原始的包裝,以及保持常溫 常濕、避免陽光直射、遠離任何腐蝕性氣體. 產品需盡快完全地使用完,建議最慢不要超過



交貨後6個月.產品經拆封後,全部的數量都需迅速地使用完.

The products shall be stored in the original packaging and kept at room temperature and humidity, out of direct sunlight, and away from any and all corrosive gas. The products shall be completely used as soon as possible, but no longer than 6 months from the date of delivery. Once product packaging is opened, the complete quantity of such products shall be promptly used.